Series: SEAFP/SEAM
Description: 1.27mm x 1.27mm grid interconnect system, 7 mm Stack Height

Connector Overview

SEAFP/SEAM is a 1.27mm x 1.27mm pitch interconnects system for elevated high-speed board-to-board applications. The open pin field design allows for dual signaling. The SEAFP/SEAM Series is designed in 4, 6, 8, and 10 row open pin field arrays. Pins per row selections designed include 10, 20, 30, 40, or 50. This report reflects only the hi-speed electrical characteristics specific to a mated 7mm stack height SEAFP/SEAM test system.

Connector System Speed Rating

SEAFP/SEAM Series, 1.27mm x 1.27mm (.050" x .050") pitch interconnect, 7mm Stack Height.

Signaling	Speed Rating
Single-Ended: 1:1 S/G	**11.5 GHz/ 23Gbps**
Single-Ended: 2:1 S/G	**11 GHz/ 22Gbps**
Differential: Optimal Horizontal	**11 GHz/ 22Gbps**
Differential: Optimal Vertical	**11 GHz/ 22Gbps**
Differential: High Density Vertical	**11.5 GHz/ 23Gbps**

The Speed Rating is based on the -3 dB insertion loss point of the connector system. The -3 dB point can be used to estimate usable system bandwidth in a typical, two-level signaling environment.

To calculate the Speed Rating, the measured -3 dB point is rounded up to the nearest half-GHz level. The up rounding corrects for a portion of the test board’s trace loss, since a short length of trace loss is included in the loss data in this report. The resulting loss value is then doubled to determine the approximate maximum data rate in Gigabits per second (Gbps).

For example, a connector with a -3 dB point of 7.8 GHz would have a Speed Rating of 8 GHz/ 16 Gbps. A connector with a -3 dB point of 7.2 GHz would have a Speed Rating of 7.5 GHz/15 Gbps.